

**WEST****Freeform Search****Database:**

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 IBM Technical Disclosure Bulletins

**Term:**

(decapsulat\$3 near5 fluid) same (integrated circuit package or "IC")

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25

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USPT,PGPB,JPAB,EPAB,DWPI,TDBD	(decapsulat\$3 near5 fluid) same (integrated circuit package or "IC")	2	<u>L5</u>
USPT,PGPB,JPAB,EPAB,DWPI,TDBD	l1 and (circuit board)	1	<u>L4</u>
USPT,PGPB,JPAB,EPAB,DWPI,TDBD	l2 not l1	6	<u>L3</u>
USPT,PGPB,JPAB,EPAB,DWPI,TDBD	(decapsulat\$3 or remov\$3 near3 encapsulat%4) same (integrated circuit package or "IC")	17	<u>L2</u>
USPT,PGPB	(decapsulat\$3 or remov\$3 near3 encapsulat%4) same (integrated circuit package or "IC")	11	<u>L1</u>